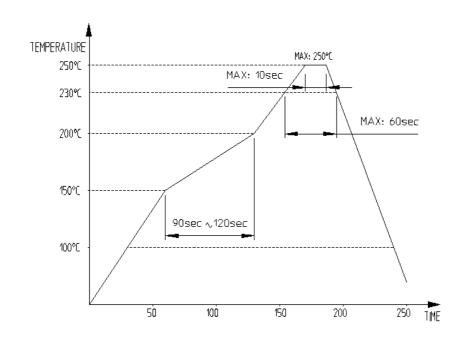
REV	COUNT DESCRIPTION OF REVISIONS BY CHKD DATE REV COUNT					COUNT	DES	DESCRIPTION OF REVISIONS BY CHKD DATE							
1	- Revised		BJH	LHJ	18.03.16										
<u>/2\</u>	- Revised		HMY	LHJ	18.04.09										
	APPLICABLE S	STANDARD													
RATING CURRENT				DC 1.25A max. for each power pin (i.e. A1, A4, A9, A12, B1, B4, B9, B12) DC 0.25A for the other pins											
VOLTAGE				20V AC											
	OPERATING O		-	-40℃ ~ +85℃ (INCLUDING TEMP. RISE), 95% RH max. (NON-CONDENSING) -10℃ ~ +60℃ (WITH PACKING), 15% ~ 70% RH											
Para. Test Description				Test Procedure						Test Requirement					Α
1	I Evamination of broduct I			ilA 364-18 isual inspection						No physical damage.					c
Electrical Requirements												1			
2	Low Level Contact Resistance			EIA 364-23 Measure at 20mV max open circuit at 100mA (DC OR 1000Hz). 4-wire measurement is required and the resistance of PCB termination shall be deducted from the reading.						Initial: 40mΩ max for each contact After test: 50mΩ max for each contact					
3	Diele Withstandi	Measur unmate	EIA 364-20 Measure per Method B with unmated condition. 100V AC RMS for 1minute at sea level.						No disruptive discharge.					_	
4	Insulation	EIA 364-21 500V DC with unmated and mated condition.						1	100MΩ min.					-	
Mech	anical Requi	rements													l
5	Insertio	EIA 364-13 Measure at 12.5mm/minute min.						Ir	Initial & after test : 5N ~ 20N O -						
6	Extraction	on force	EIA 364-13 Measure at 12.5mm/minute min.							Initial: 8N ~ 20N After test: 6N ~ 20N (with virgin plug)					-
7	7 Durability M			EIA 364-09 Mated 10,000 times Mechanically operated: 500cycles/hr Mating stroke: 2.75mm Insertion, extraction force shall be measured at a maximum speed of 12.5mm/min					(2	① No physical damage. ② Insertion force - Initial & after test: 5N ~ 20N ③ Extraction force - Initial: 8N ~ 20N - After test: 6N ~ 20N (with virgin plug)					_
8	Air-	Leak	Input air pressure : 20±5% KPa for 5sec.						Ir	Inspection leakage: 0.3% (60Pa) max.					-
9	IP.	X8		nmersion in the water the depth of 1.5m for 30min.						No water penetration.					-
10	Random	Vibration	Test Co Mated s betwee 15minu	IA 364-28 est Condition VII, Test Letter D lated specimens to 3.10 G's RMS etween 20 to 500Hz 5minutes in each of 3 mutually erpendicular planes.						No physical damage. No discontinuity of 1us of longer duration when mated connector during test.					_
REMARKS					DRAFT DESIG		IGN	CHECK APPRO		OVAL	RELE	EAS	E		
Unless otherwise specified, refer to the specifications for USB Type-C, EIA 364				S.H	.LIM	S.H.	.LIM	H.J.LEE	T.S.	KANG					
					18.02.19 18.02.1			2.19	19 18.02.19 18.02.19						
NOTE) (QT : QUALIFICA	TION TEST, AT	ASSUF	RANCE T	EST, O	Applica	ıble Tes	t		· -			-		
DWG NO CL NO				6240-0016-6			3	CX90MWD2-24P							
HS HIROSE KOREA.CO.,LTD					PRODUCT SPECIFICATION 1/								_		
IIV DINUSE KUREA.CU.,LID							PRODUCT SPECIFICATION '/							(3	

Para. Test Description		Test Procedure	Test Requirement	QT	ΑТ			
Enviro	onmental Requirements							
11	Temperature Life	EIA 364-17, Method A 105°C without applied voltage for 120hours.	No physical damage.	0	-			
12	Cyclic Temperature and Humidity	EIA 364-31 25±3°C at 80±3% RH for 1hour. 65±3°C at 50±3% RH for 1hour. Thermal ramp: 0.5hour Number of cycles: 24cycles	No physical damage.	0	_			
13	Thermal Shock	EIA 364-32, Test Condition I 10cycles -55°C and +85°C	No physical damage.					
14	Solderability	EIA 364-52 Dwell in 245±5°C of the solder bath for 5sec.	Solder coverage shall be 95% min. of the immersed surfaces.	0	_			
15	Salt Spray	EIA 364-26 5% of NaCl in 35℃ for 48hours.	No corrosions that affect to the connector operation.	0	-			
16 REMAR	Reflow test	Reflow profile [Fig.1] Peak 250°C max for 10sec 2times.	① Co-planarity Before & after Reflow 0.08 max. ② No deformation of mold ③ No shape of blister and popcorn	0	_			

REMARKS



[Fig.1] REFLOW TEMPERATURE

 NOTE) QT : QUALIFICATION TEST, AT : ASSURANCE TEST, O : Applicable Test

 DWG NO
 CL NO
 PART NO

 ELC4-632534
 CL 6240-0016-6
 CX90MWD2-24P

HIS HIROSE KOREA.CO.,LTD

PRODUCT SPECIFICATION

Qualification Test Sequence Table											
Para.	Test Description		В	С	D	E	F	G	Н	I	J
1	Examination of Product		1	1	1	1	1	1	1	1	1
2	Low Level Contact Resistance			2,4	2,10	2,4	2,4	2,4		2,4	
3	Dielectric Withstanding Voltage				3,11						
4	Insulation Resistance				4,12						
5	Insertion Force				5,8						
6	Extraction Force				6,9						
7	Durability				7						
8	Air-leak										
9	IPX8		2								
10	Random Vibration			3							
11	Temperature Life					3					
12	Cyclic Temperature and Humidity						3				
13	Thermal Shock							3			
14	Solderability								2		
15	Salt Spray									3	
16	Reflow Test										2

Remarks

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¹⁾ Numbers in the table above indicate the sequence corresponding to each test group.